



The Power of LED Light

Typical Electrical & Optical Characteristics (IF=350mA and Ta=25℃)

Part-No.	Dom Wavelen or C0	. ,	Forward Voltage (V)		(lm)		Rever- se Cur- rent (µA)	50% Power Angle
	Min	Тур	Min	Max	Min	Тур	max	Тур
M11E3006	520	530	3.3	4.0	65	75	10	120

- 1. Tolerance of measurement of luminous flux: +/-15%
- 2. Tolerance of measurement of dominant Wavelength: +/-1nm
- 3. Tolerance of measurement of CCT (Correlated color temperature +/- 200K
- 4. Tolerance of measurement of forward voltage +/-0,1V

Technical Dimensions Cathode(-) Anode(+) Cathode Anode







Features

Contour Lights Garden Lighting **Genral Lighting** Reading Lights

Absulut Maximum Ratings (Ta=25℃)

Items	Symb ols		Unit
		Green	
Power Dissipation	Pd	1600	mW
Forward Current	lf	400	mA
Peak Forward Current	Ifp	500	mA
Reverse Voltage	Vr	5	V
LED Junction Temperature	Tj		${\mathcal C}$
Operating Temperature	Topr	-30℃ ~ +85℃	${\mathbb C}$
Storage Temperature	Tstg	-40℃ ~ +100℃	C

^{*} Pulse width ≤ 0,1msec duty ≤ 1/10

SMD DIAMOND XEON POWER EMITTER LED

Part No.: M11E3006

Customer:

DRW: CHKD Wilson MATL: Wilson **TOLERANCE** Mason 12.07.2010 Jason DATE APPD: Schumi FINISH Sheet No. 1 from 10 Jamy











The Power of LED Light

BIN GUIDE / HIGH POWER

Tolerance of measurement of luminous Flux is +/- 15%

Code	Luminous	Flux Range	Code	Luminous I	Flux Range
Code	min	max.	Code	min	max.
Α	1	2	P2	70	80
В	2	2,5	M1	80	90
С	2,5	3,2	M2	90	100
D	3,2	4	N1	100	110
Е	4	5	N2	110	120
F	5	6,2	P1	120	130
G	6,2	7,7	P2	130	140
Н	7,7	9,6	Q1	140	150
J	9,6	12	Q2	150	160
K	12	15	R1	160	170
L1	15	19	R2	170	180
L2	19	24	S1	180	200
M1	24	30	S2	200	220
M2	30	40	T1	220	240
N1	40	50	T2	240	260
N2	50	60	U1	250	280
P1	60	70			
		В	Τ	G/E	F

Code	CCT	Range	Code	CCT	Range
Code	Min	Max	Code	Min	Max
А	2700	2900	М	4900	5100
В	2900	3100	N	5100	5500
С	3100	3300	Р	5500	6000
D	3300	3500	Q	6000	6500
E	3500	3700	R	6500	7000
F	3700	3900	S	7000	7500
G	3900	4100	T	7500	8000
Н	4100	4300	U	8000	9000
J	4300	4500	V	9000	10000
K	4500	4700	W	10000	12000
L	4700	4900			
Toloranco of moa	surement of CCT	ic 1/100K	•		

Tolerance of measurement of CCT is +/-100K.

FI		,0	,	U												_
			В		Н	G	i/E		F		Y	C	/P	R	:/U	
Color	Code	Min	max	Min	max	Min	max	Min	max	Min	max	Min	max	Min	max	of nm
	00	450	455	490	495	515	520	560	565	580	583	600	605	620	625	measurement elength is +/-1
)1	455	460	495	500	520	525	565	570	583	586	605	610	625	630	rem is
)2	460	465	500	505	525	530	570	575	586	589	610	615	630	635	asu
)3	465	470	505	510	530	535	575	580	589	592	615	620	635	640	me
)4	470	475	510	515	535	540			592	595			640	645	of vav
	5	475	480			540	545			595	598			645	650	Tolerance of measur
	06	480	485			545	550							650	655	lera
	7	485	490			550	555							655	660	
	8					555	560							660	665	
DR	:W	Ja	son	CH	IKD	Wil	lson	MA	ATL:	Wil	son	TOLE	RANCE	Ma	son	
AP	PD:	Sch	numi		•			FIN	IISH	Ja	my		•		Shee	et No.

DATE

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Part No.: M11E3006

Customer:

12.07.2010

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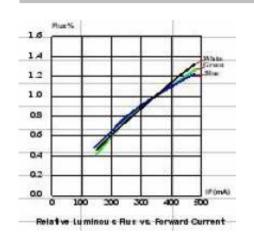


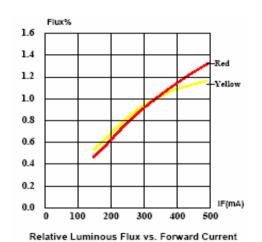


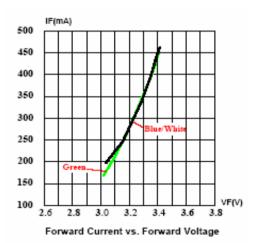


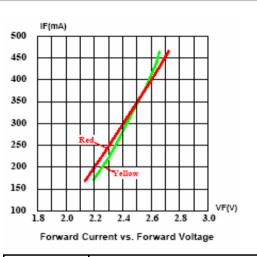
The Power of LED Light

Typical Electrical / Optical Characteristics Curves (Ta=25℃ Unless otherwise noted)

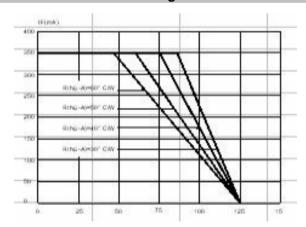








Current	Derating	Curves
O GI I O I I C	Doiating	O u. 100



Code	Forward Vo	oltage Rank
Code	Min.	Max.
А	1,6	1,8
В	1,8	2,0
С	2,0	2,2
D	2,2	2,4
E	2,4	2,6
F	2,6	2,8
G	2,8	3,0
Н	3,0	3,2

Tolerance of measurement of forward voltage is +/-0,1V

Code	Forward Vo	oltage Rank
Code	Min.	Max.
J	3,20	3,40
K	3,40	3,60
L	3,60	3,80
М	3,80	4,00
N	4,00	4,20
Р	4,20	4,40
Q	4,40	4,60
R	4,60	4,80

SMD DIAMOND XEON POWER EMITTER LED

Part No.: **M11E3006**

Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	12.07.2010
APPD:	Schumi			FINISH	Jamy		Shee	t No.	3 from 10



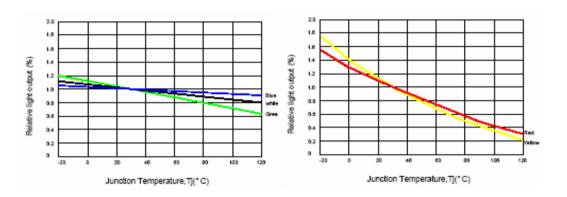


The Power of LED Light



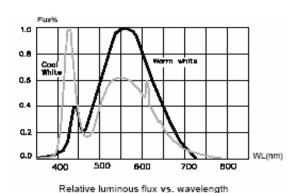


Light Output Characteristics



Wavelength Characteristics

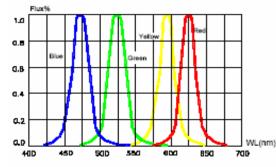
Wilson



Jason

Schumi

CHKD

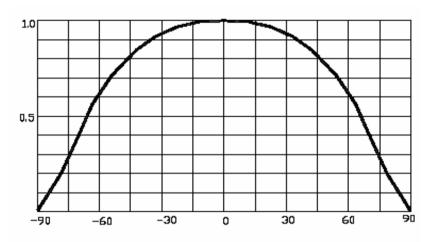


Relative luminous flux vs. wavelength

MATL:

FINISH

Typical Representative Spatial Radiation Paddern of single LED



Angular Displacement(degress)

SMD DIAMOND XEON POWER EMITTER LED

M11E3006 Part No.:

Customer:

Wilson TOLERANCE Mason 12.07.2010 DATE Sheet No. 4 from 10 Jamy

DRW:

APPD:











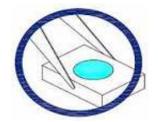
The Power of LED Light

Handling Informations

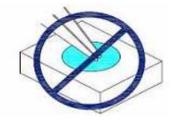
- 4. The outer diameter of the TOP LED pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although ist characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of th LED.

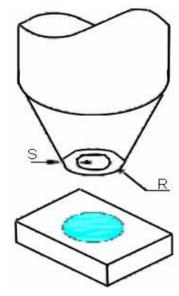
1. Handle the component along the side surfaces by using forceps or appropriate tools







2. Do not directly touch or handle the silicone lens surfance. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratsch the silicone lens or damage the internal circuitry.



SMD DIAMOND XEON POWER EMITTER LED

Part No.: **M11E3006**

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DRW: **CHKD** Wilson MATL: Wilson TOLERANCE Mason DATE 12.07.2010 Jason APPD: Schumi **FINISH** Sheet No. 5 from 10 Jamv











Moisture Proof Packing

In Order to prevent moisture absorption into DIAMOND = TOP LED / XEON POWER during the transportation and storage. DIAMOND TOP-LED / XEON-POWER LED is packed in a moisture barrier bag. Desiccants and humidity indicator are packed together with DIAMOND TOP-LED / XEON-POWER LED as the secondary protection. The indication of humidity card provides the information of humidity within TOP Packing.

Storage

Shelf life in original sealed bag in storage condition of <40°C and 90% RH is 12 mounths. Baking is re quired whenever shelf life is expired. Before opening the packaging please check wether bag leak air or not. After opening the DIAMOND TOP-LED / XEON POWER LED must be storad under the condition <30°C and 60% RH. Under this condition DIAMOND TOP-LED / XEON POWER LED must be used (subject to reflow) within 24-hours after bag opening, and re-baking is required when exceeding 24 hours. For baking, place DIAMOND TOP-LED / XEON POWER LED in oven at temperature 75°C +/-5°C and relative hu midity <10%RH, for 24 hours. Take out the material from packaging bag for re-bake. Do not open the door of oven frequently during the baking process.

Manual soldering (We do not recommend this method strongly).

No mechanical stress should be exerted on the resin portion of DIAMOND TOP-LED / XEON POWER during soldering.

Handling of DIAMOND TOP-LED / XEON POWER LED should be done when the package has been cooled down to below 40℃ or less. This is to prevent the DIAMOND TOP-LED / XEON POWER failures due the thermal-mechanical strss during handling.

Reflow soldering should not be done more than one time.

No stress should be exerted on the package during soldering.

Electrostatic Discharge and Surge current.

Electrostatic discharge (ESD) or surge current (EOS) may damage LED.

Precautions such as ESD wrist strap, ESD shoe strap or antistatic gloves must be worn whenever handling DIAMOND TOP-LED / XEON POWER LED.

All devices, equipment and machinery must be prpertly grounded.

It is recommended to perform electrical test to screen out ESD failures in final inspection.

It is important to eliminate the possibility of surge current during circuity design.

Heat Management

Heat manegement of DIAMOND TOP-LED / XEON POWER must be taken into into consideration during the design stage of DIAMOND TOP-LED / XEON POWER LED application. The current should be de-rated appropriately by refering to the de-rating curve attached on each product specification.

SMD DIAMOND XEON POWER EMITTER LED

Part No.: **M11E3006**

DRW: CHKD Wilson MATL: Wilson **TOLERANCE** Mason 12.07.2010 Jason DATE APPD: Schumi **FINISH** Sheet No. 6 from 10 Jamy

email: info@edcon-components.com

Customer:



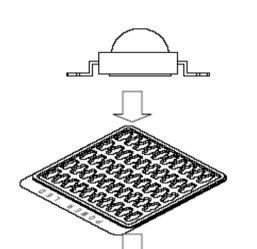




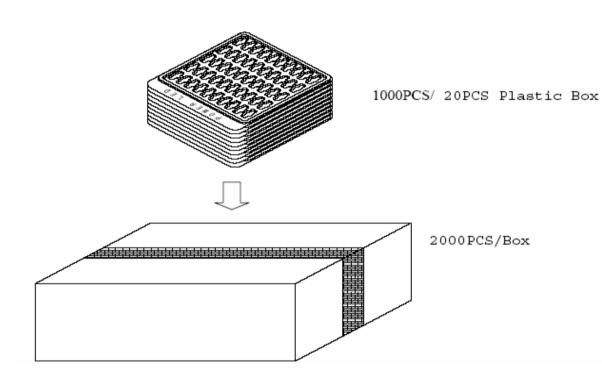




Packing Specifications



50PCS/ Plastic Box



SMD DIAMOND XEON POWER EMITTER LED

Part No.: M11E3006

Wilson MATL: DRW: CHKD Wilson TOLERANCE Mason DATE 12.07.2010 Jason APPD: FINISH Schumi Sheet No. 7 from 10 Jamy

Customer:











Ordering Informations

Serie	Color Code	ROHS	Packing				
M11E3006	GR	R	TR				

GR	R = ROHS	TR= TAPE
=	Conform	REEL
Green	N= NON	BU = Bulk-
'	ROHS	Ware

SMD DIAMOND XEON POWER EMITTER LED

Part No.: **M11E3006**

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DRW: CHKD Wilson MATL: Wilson 12.07.2010 Jason TOLERANCE Mason DATE APPD: Schumi FINISH Sheet No. 8 from 10 Jamy





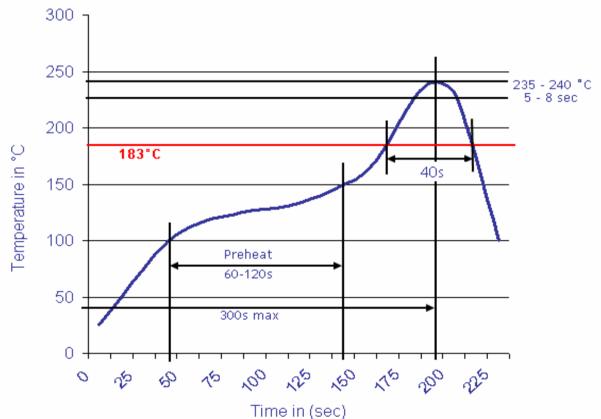






Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



SMD DIAMOND XEON POWER EMITTER LED

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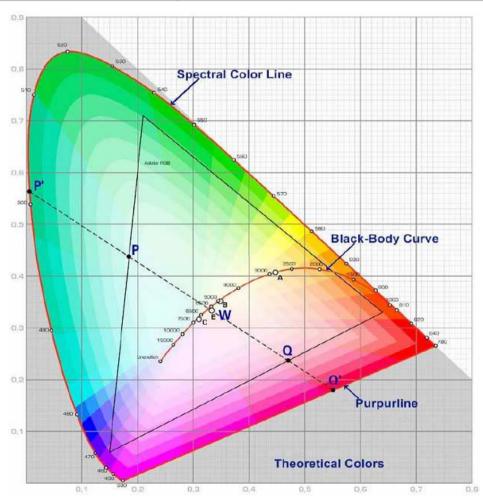






The Power of LED Light

Spectral Color Curve



SMD DIAMOND XEON
POWER EMITTER LED

Part No.: **M11E3006**

Customer:

MATL: DRW: CHKD Wilson Mason Jason Wilson TOLERANCE DATE 12.07.2010 APPD: Schumi FINISH Sheet No. 10 from 10 Jamy